

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.: 10/565916 Confirmation No.: 9371
Applicant: CHENG, *et al.*
Filed: 25/JAN/2006
TC/A.U.: 2813
Examiner: Vicki B. Booker
Docket No.: DC5157 PCT1
Customer No.: 00137
Date: 5 January 2009
For: Process for Fabricating Electronic Components Using Liquid Injection
Molding

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Sir:

In response to the office action dated June 18, 2008 please amend the above-identified application as follows.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 6 of this paper.